

# [ELECTROPLATING APPARATUS]

## Abstract

The present invention provides an electroplating apparatus that provides a turbulent current and an even fluid flow pressure of a plating solution for uniformly distributing the flow of the plating solution over a wafer. By using the electroplating apparatus of the present invention, a metal can be grown uniformly in a via hole, and a metal layer can be uniformly formed on the wafer. Therefore, non-uniformly formed metal layer and partially filled via holes can be effectively avoided.